

Use of Prototyping & Emulation in the Semiconductor Industry in 2025

Michael O' Sullivan, Cadence

1st July 2025

 cadence[®]

Cadence

An AI Computational Software Leader

OUR MISSION is to innovate technology and productivity solutions for an AI-enabled world

OUR SOLUTIONS enable engineers and scientists to bring innovative new products to life



Hyperscale
Data Centers and
Communications



Transportation,
Robotics, and
Machines



AI-Enabled
Sciences

Cadence at a Glance

An AI Computational Software Leader

CORPORATE

13,000+

Global Employees

35.3%

Revenue Invested in R&D

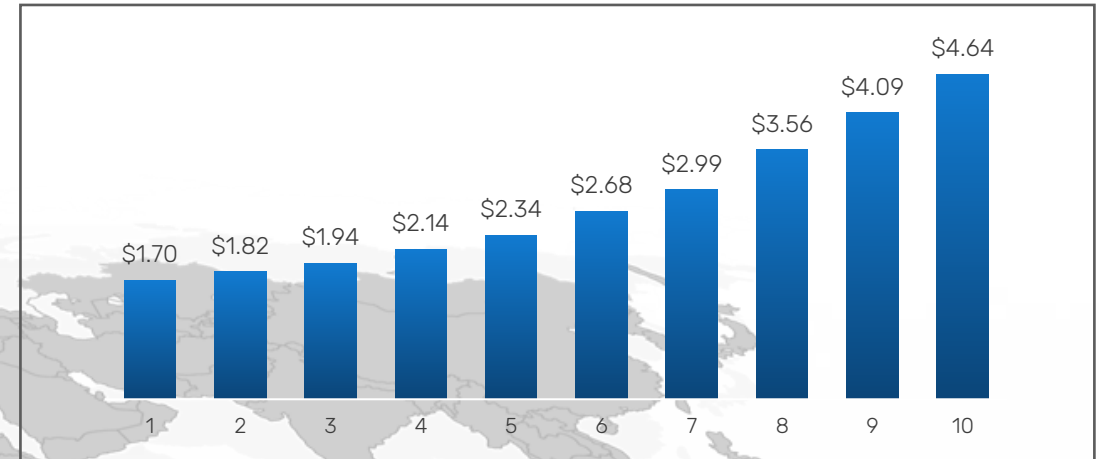
40

Global Development Centers

1600+

Patents Awarded

REVENUE (\$B)



RECOGNITIONS

Wall Street Journal's **Best Managed Companies 2025**

Time's **World's Best – Sustainable Growth Companies 2025**

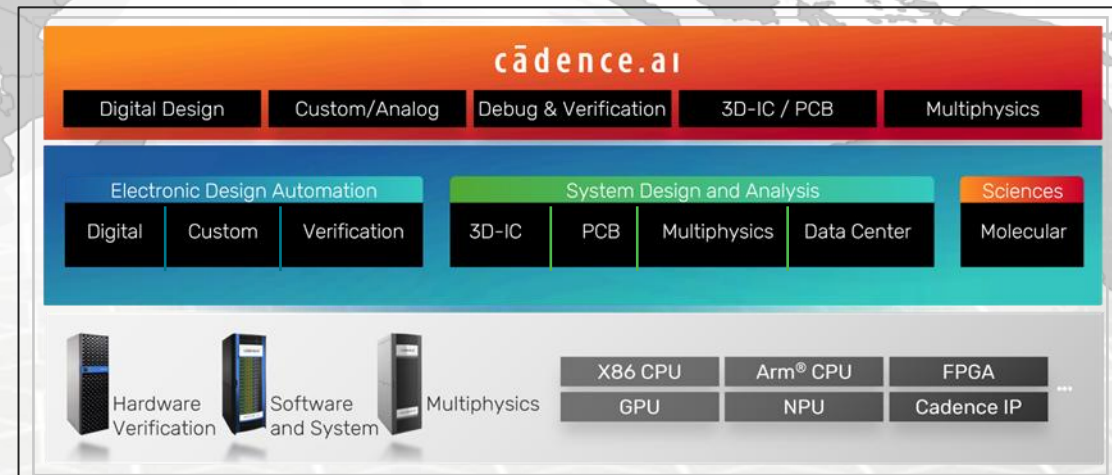
Newsweek's **America's Most Responsible Companies 2025**

Fortune's **100 Best Companies to Work For 2025**

Fast Company's **Most Innovative Companies 2024**

Time's **America's Best Mid-Sized Companies 2024**

ACCELERATED DESIGN TECHNOLOGIES

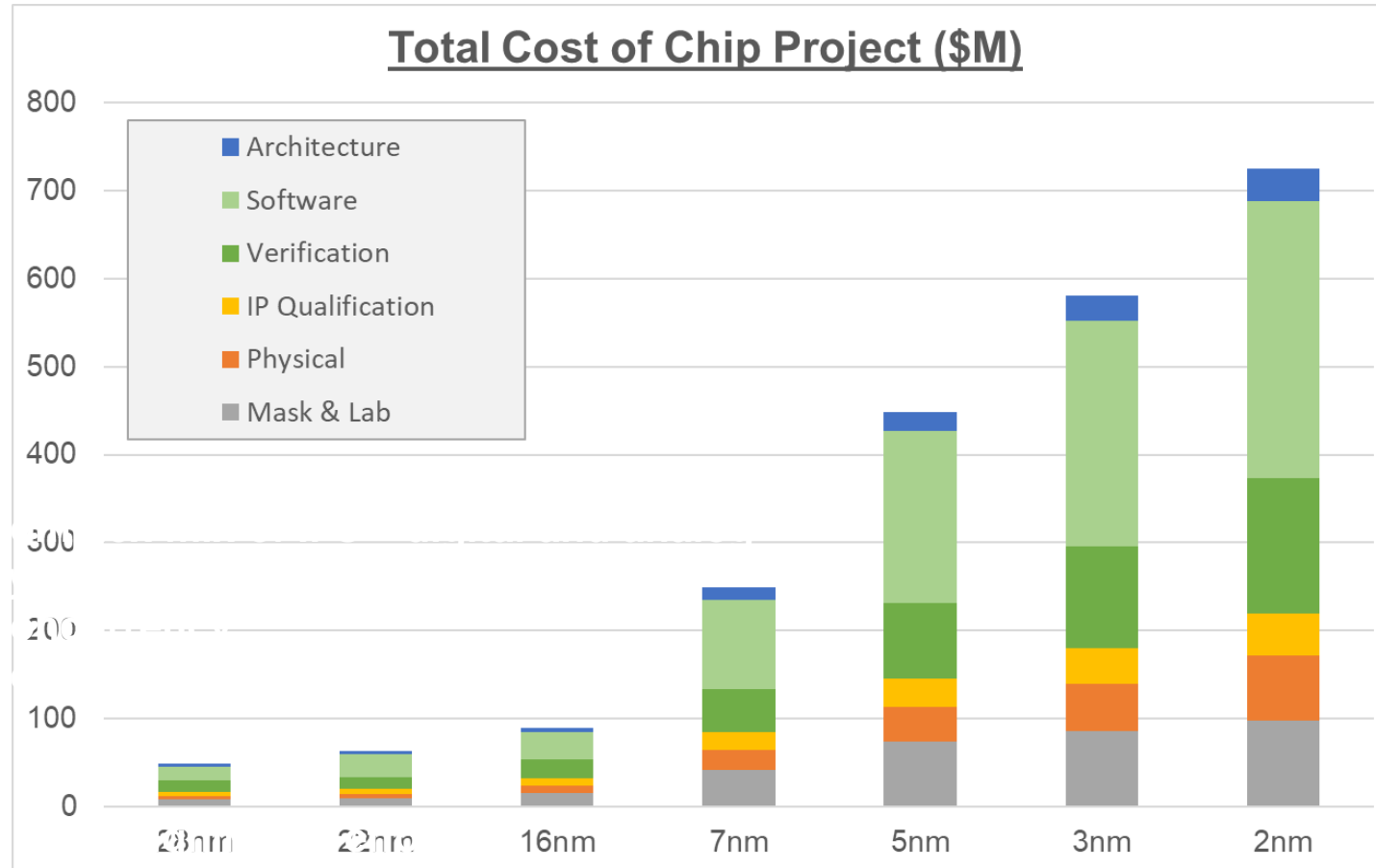


Source: Cadence Earnings Press Release, April 28, 2025
https://www.cadence.com/en_US/home/company/newroom/press-releases/pr-ir/2025/cadence-reports-first-quarter-2025-financial-results.html

Agenda

- Use of emulation/prototyping in the semiconductor industry
- Cadence platforms for emulation/prototyping
- Summary

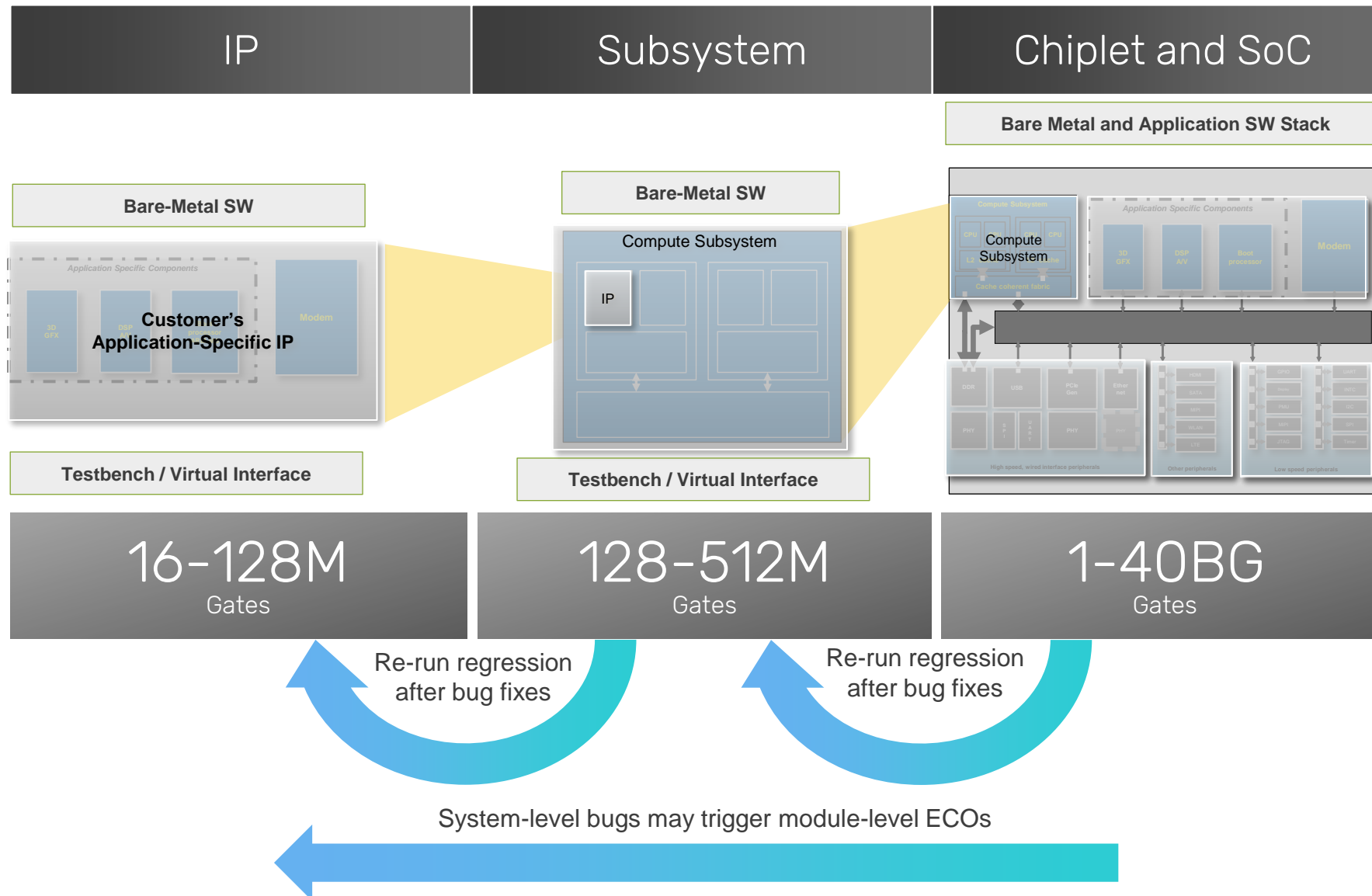
Software Verification Challenge



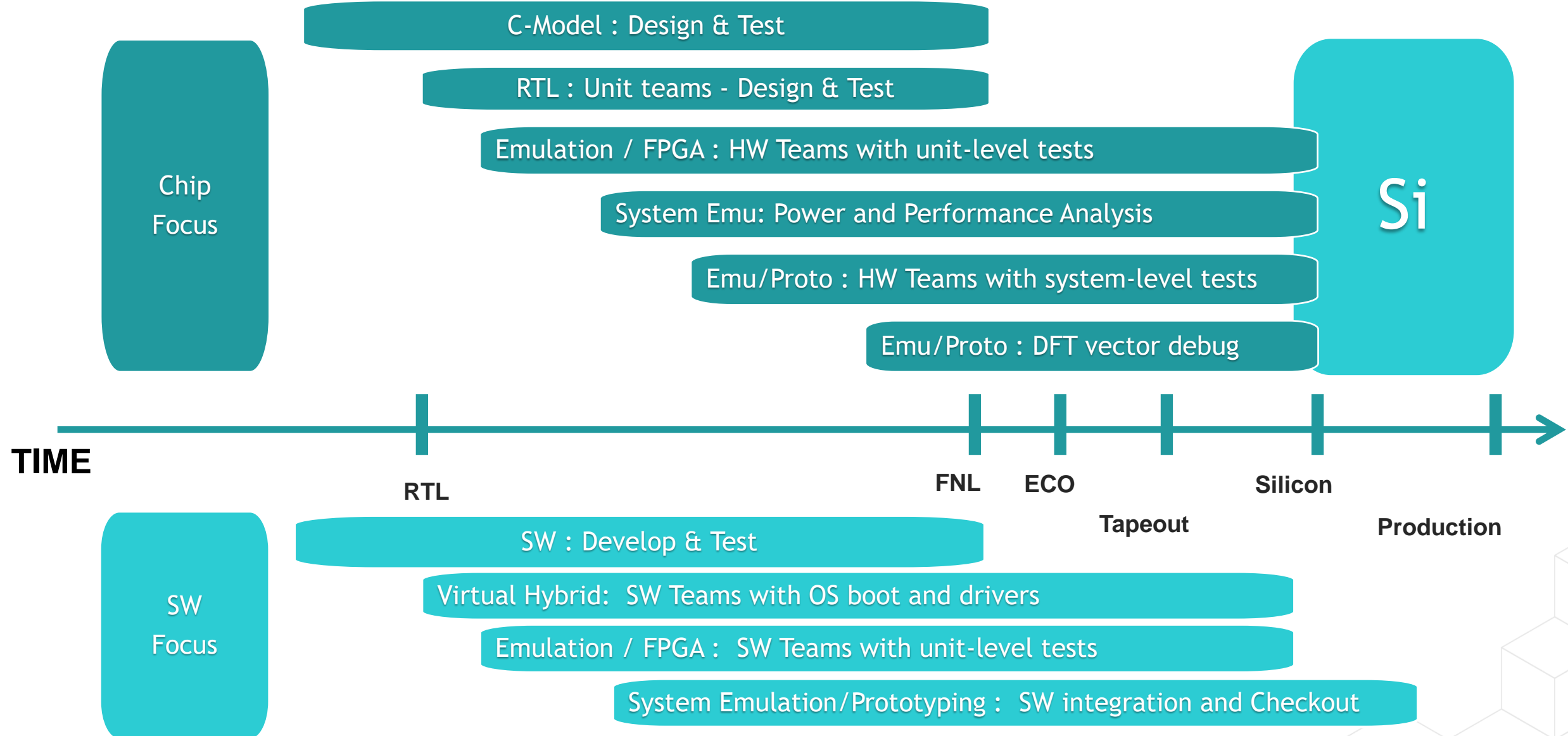
75%+ project costs in software and verification

IBS July 2022

Verification for Different Sizes of Payloads

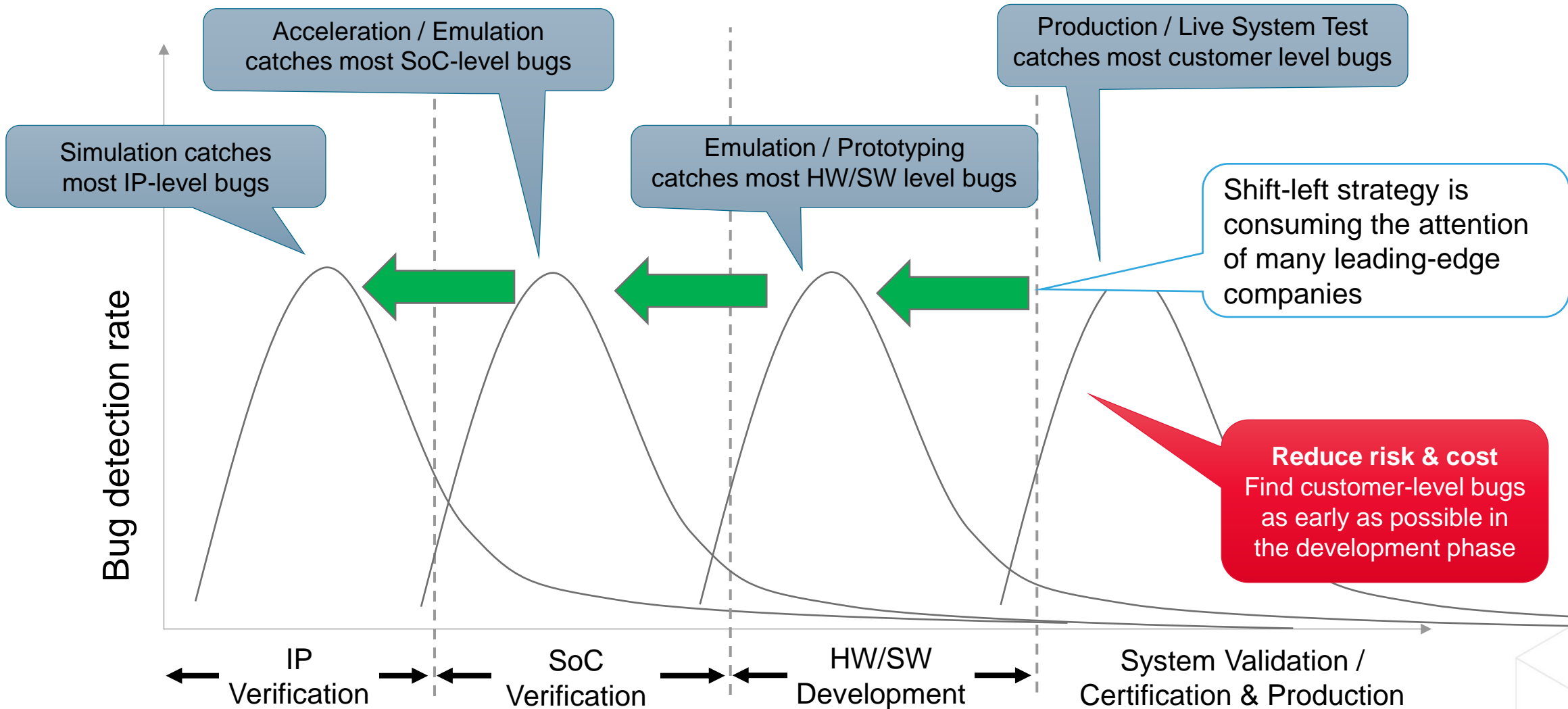


Emulation & Prototyping: D&V Methodology Example



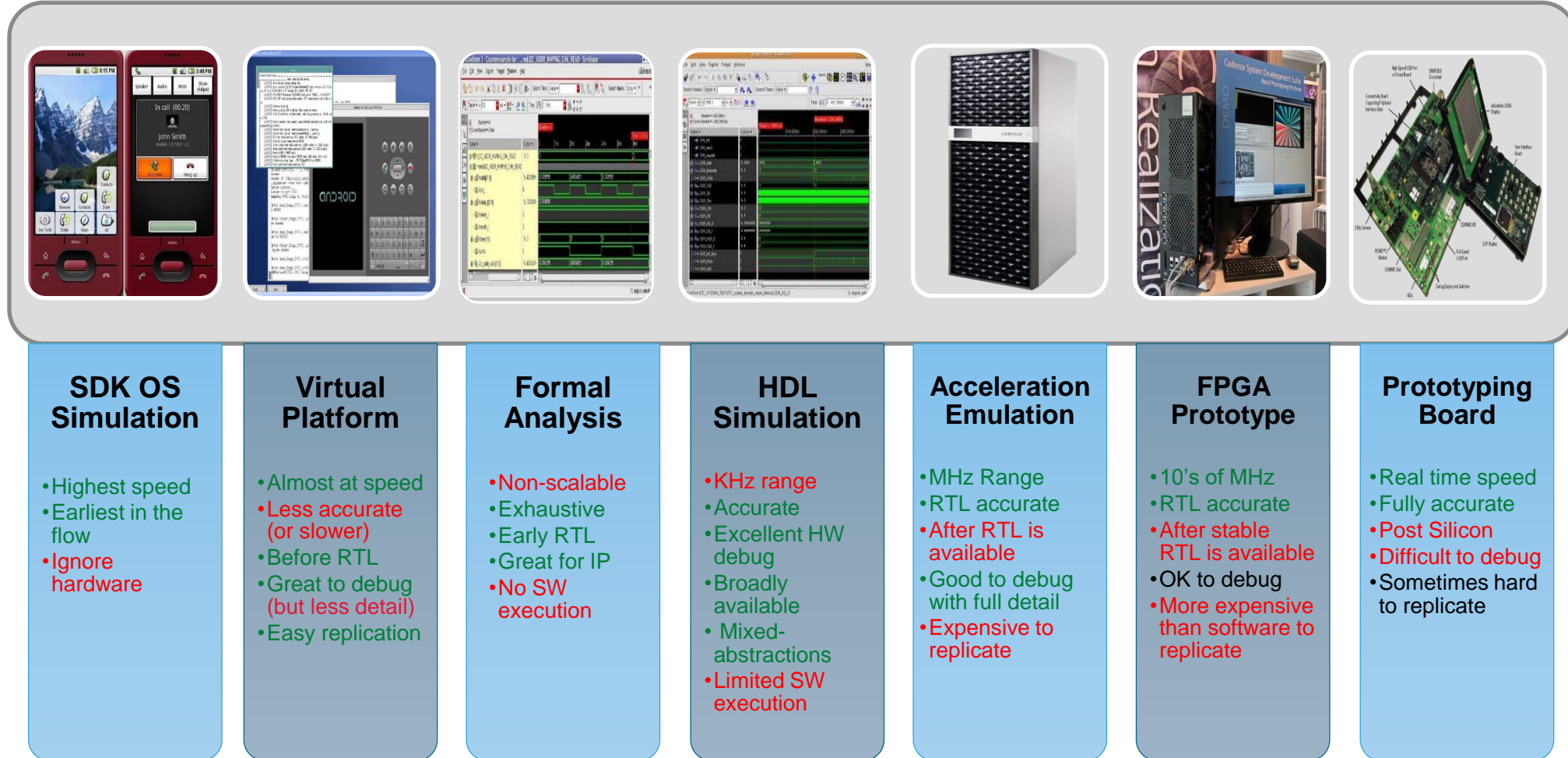
Challenge: more silicon and system development in less time

Bug detection still not as early as possible

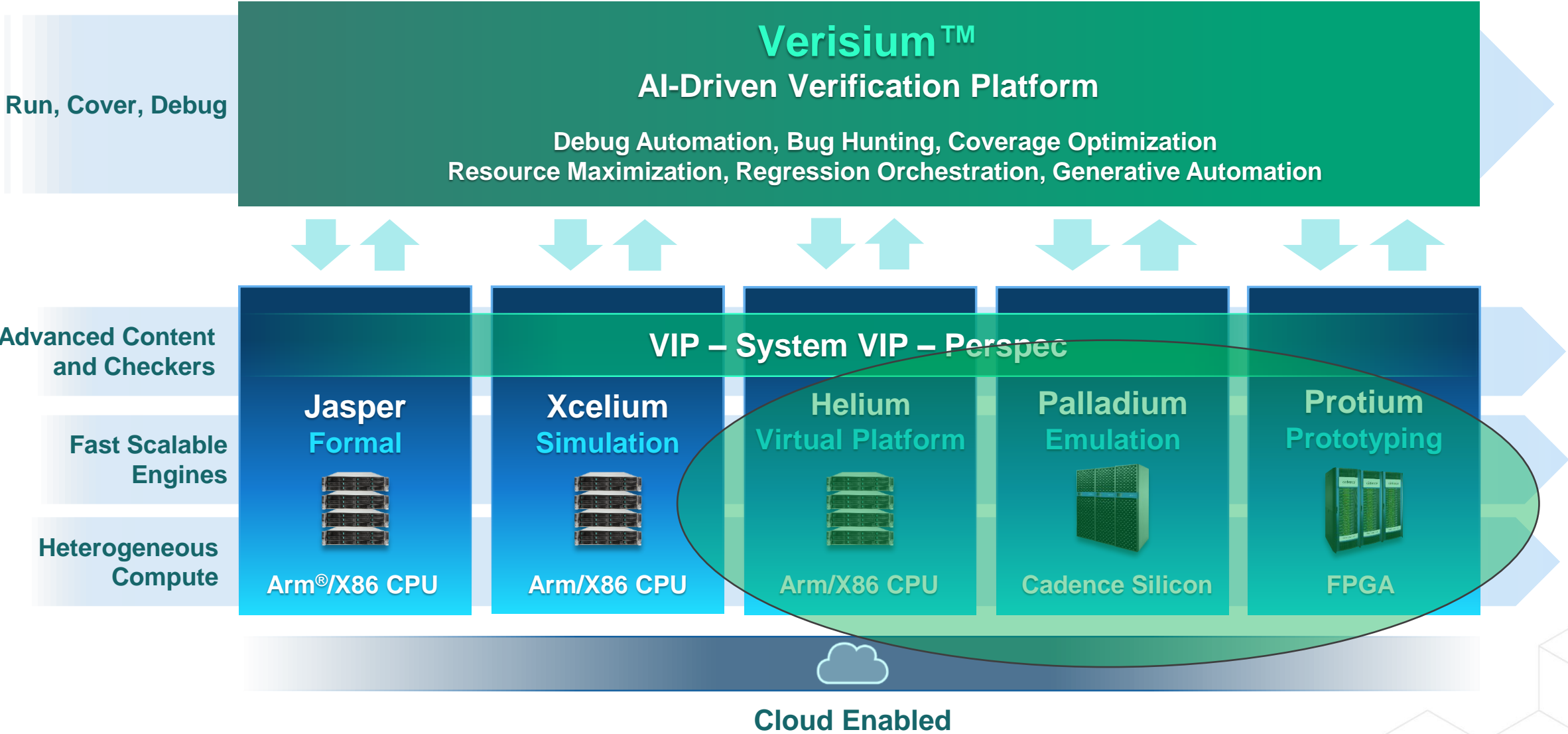


There is no “One Size Fits All”

Verification and software platforms need to interoperate



Cadence AI-Driven Verification Full Flow



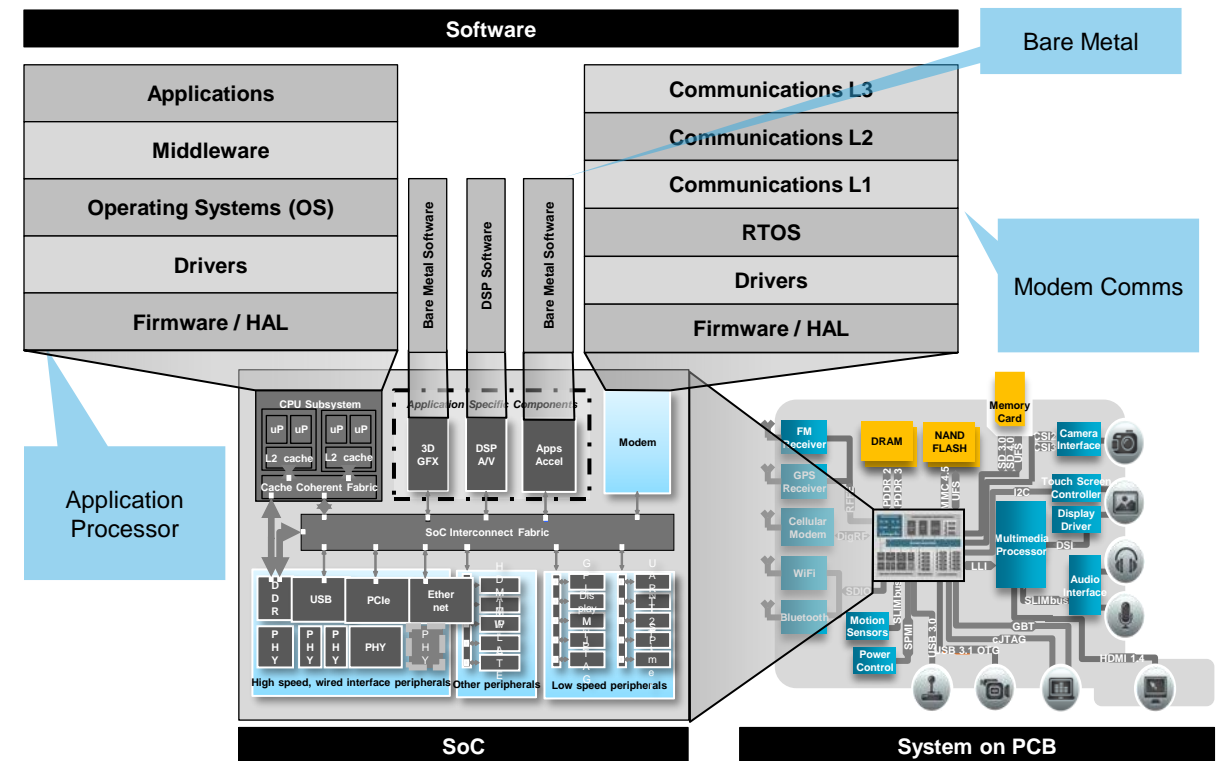
System and Chip Design Trends

Business challenges

- Time-to-market
- Development cost reduction

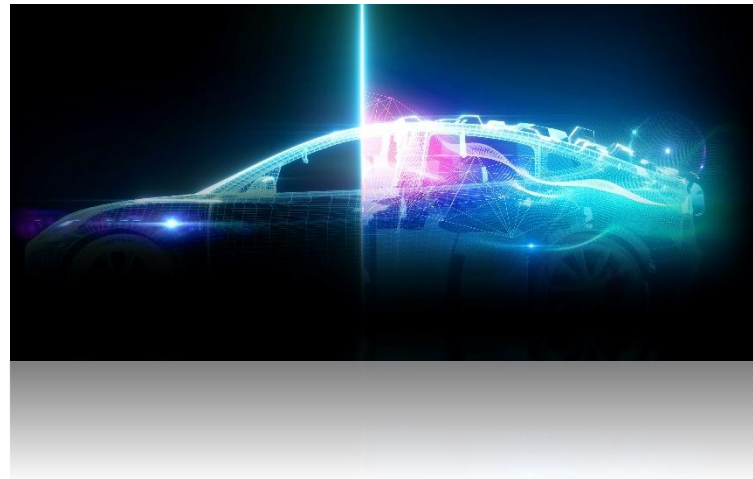
Technical challenges

- Multi-core design and verification complexity
- Integration of new IP, subsystems in derivatives
- Software stack development and bring-up
- Hardware-software convergence
- **More than 60% of effort in software**



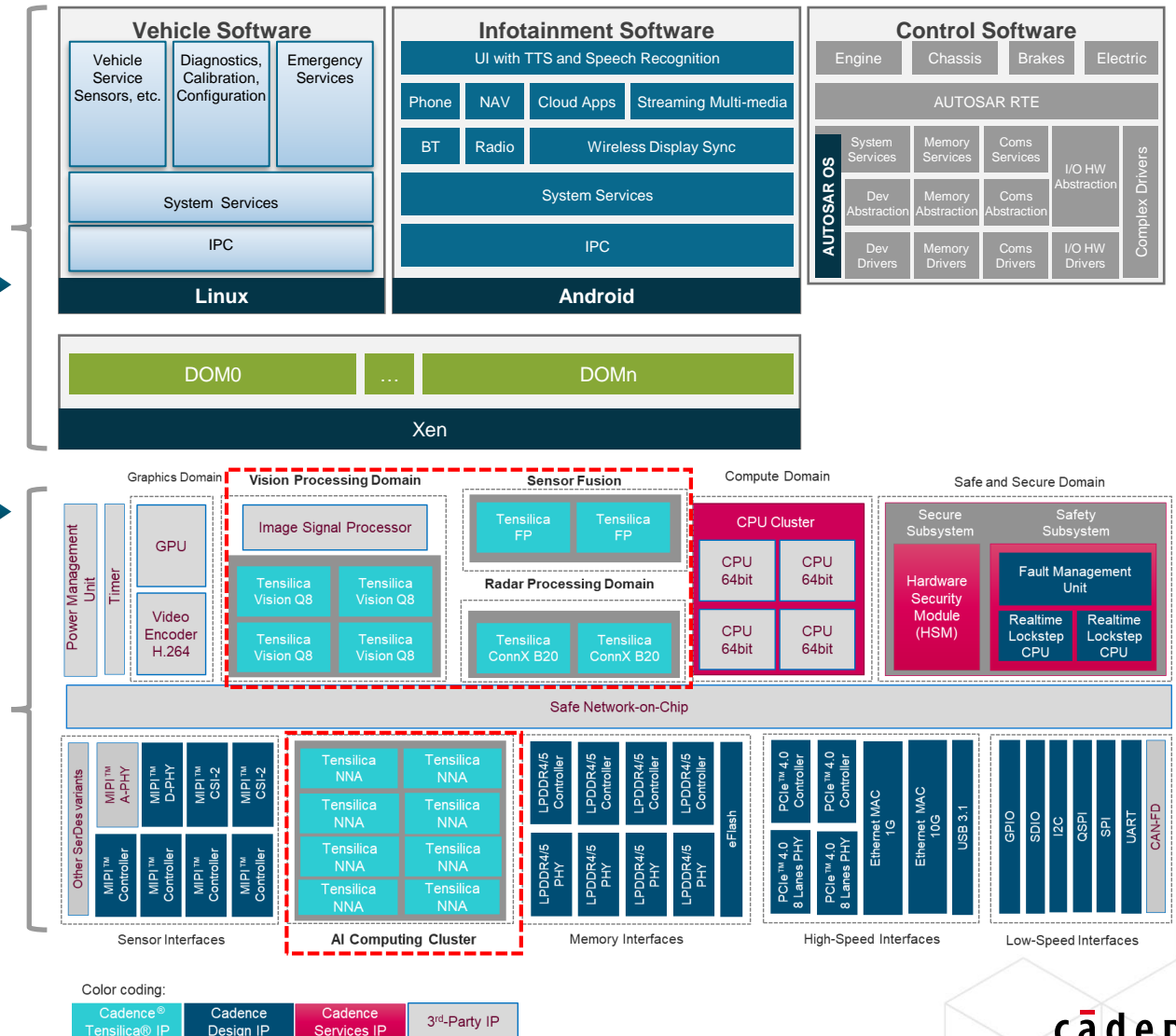
Design Trends Practical Result

Formerly separate projects must converge, software is a fundamental component



Software

Hardware



- Hardware is not complete until it works with the software and vice versa
- Teams cannot afford to work sequentially

Cadence Helium Digital Verification Process



Virtual Platforms

- Software development and verification ***in parallel with*** hardware development and verification
- Validated software simplifies verification



Hybrid Platforms

- Software development and verification ***foundationally integrated with*** hardware development and verification
- Start both before either are complete
- Accuracy and speed where you need them

Virtual Platforms

Transforming software development

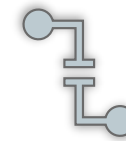


Controllability, Observability, Repeatability



Instruction Accurate

- Target software runs without changes



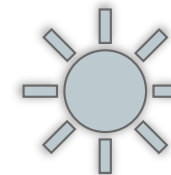
Full programmers view

- Memory, registers, and interrupts



Loosely Timed

- Fast enough for OS Boot



Available Early

- 6-12 months before silicon



All in Software

- Run on standard x86 workstations

Hybrid Platforms

Transforming software-driven verification



Mixed Accuracy

- RTL for DUT
- TLM for context



Full Programmers' View

- Memory, registers, interrupts, and pins



Mixed Abstraction

- Fast enough for OS Boot
- Detailed enough verification



Available Early

- As soon as the DUT is ready



Integrated with Hardware

- Palladium® and Protium™ platforms for capability and performance

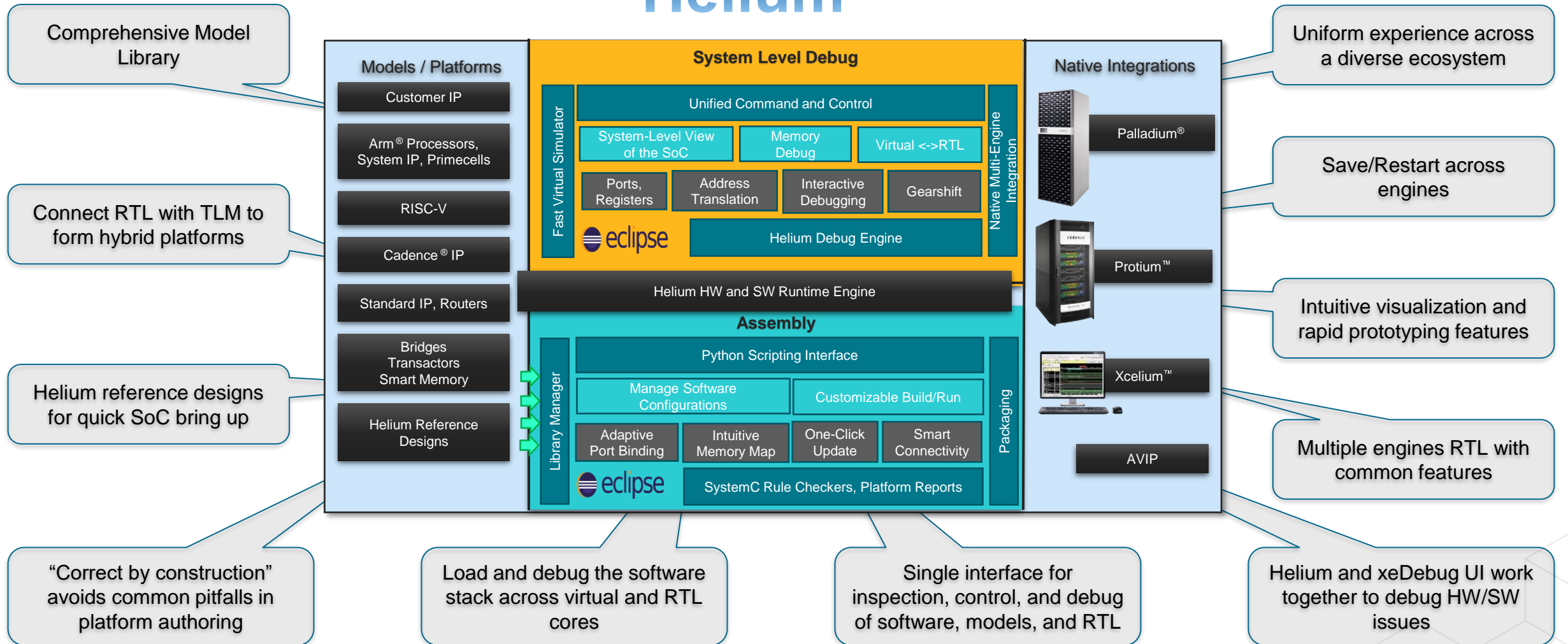


Balance of Speed and Accuracy

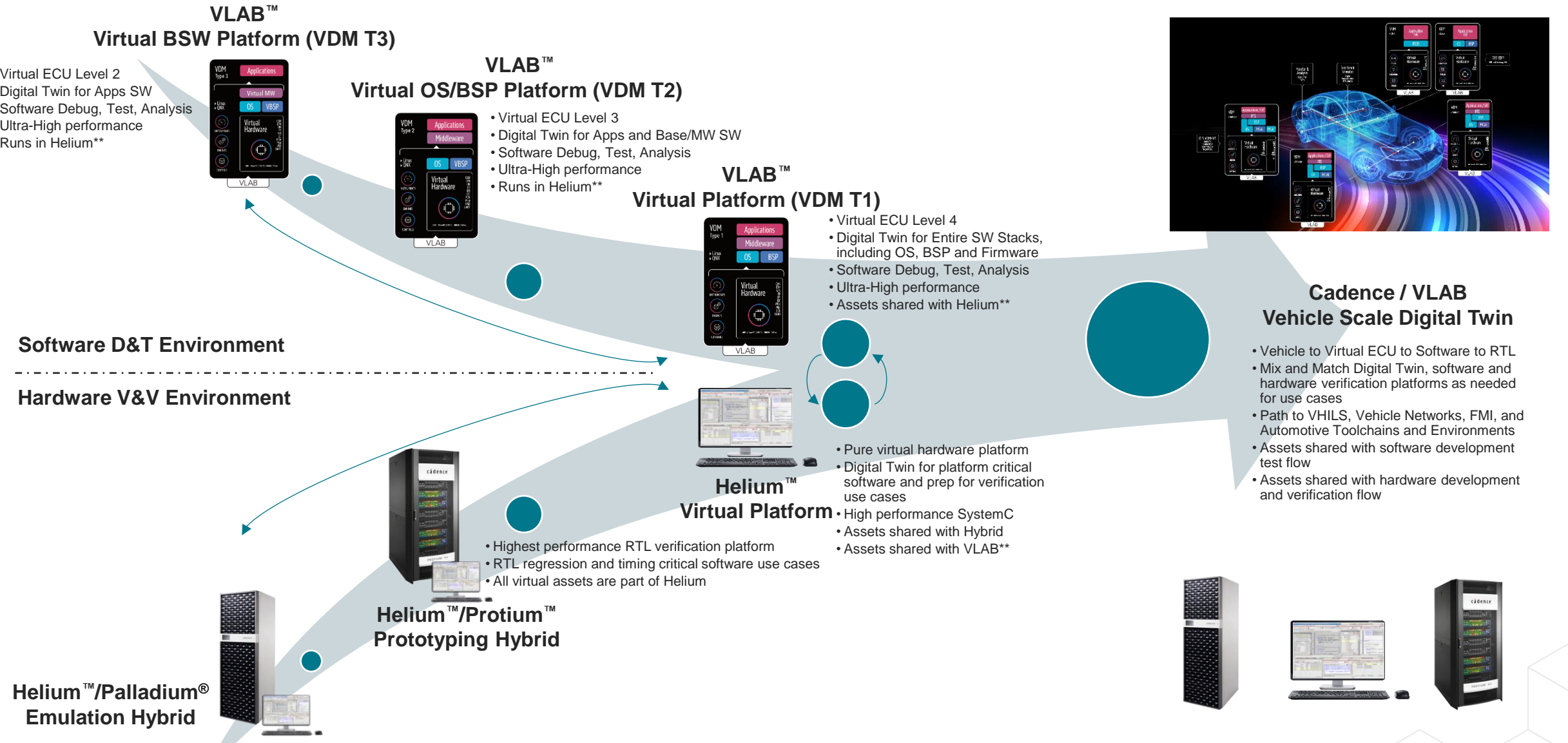
Helium Virtual and Hybrid Studio

The key to a flow that connects verification and software together

Helium™

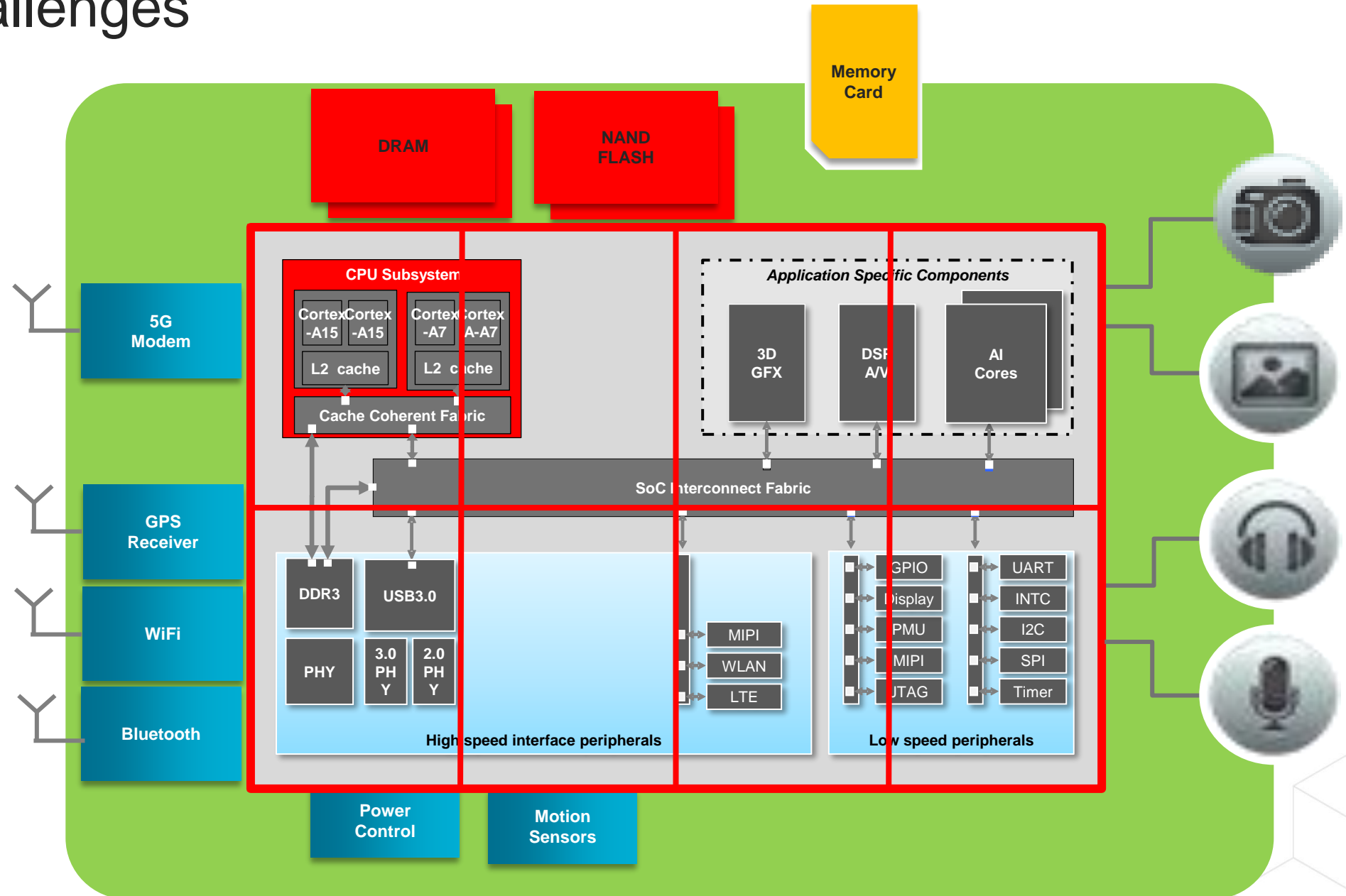


Cadence + VLAB Works



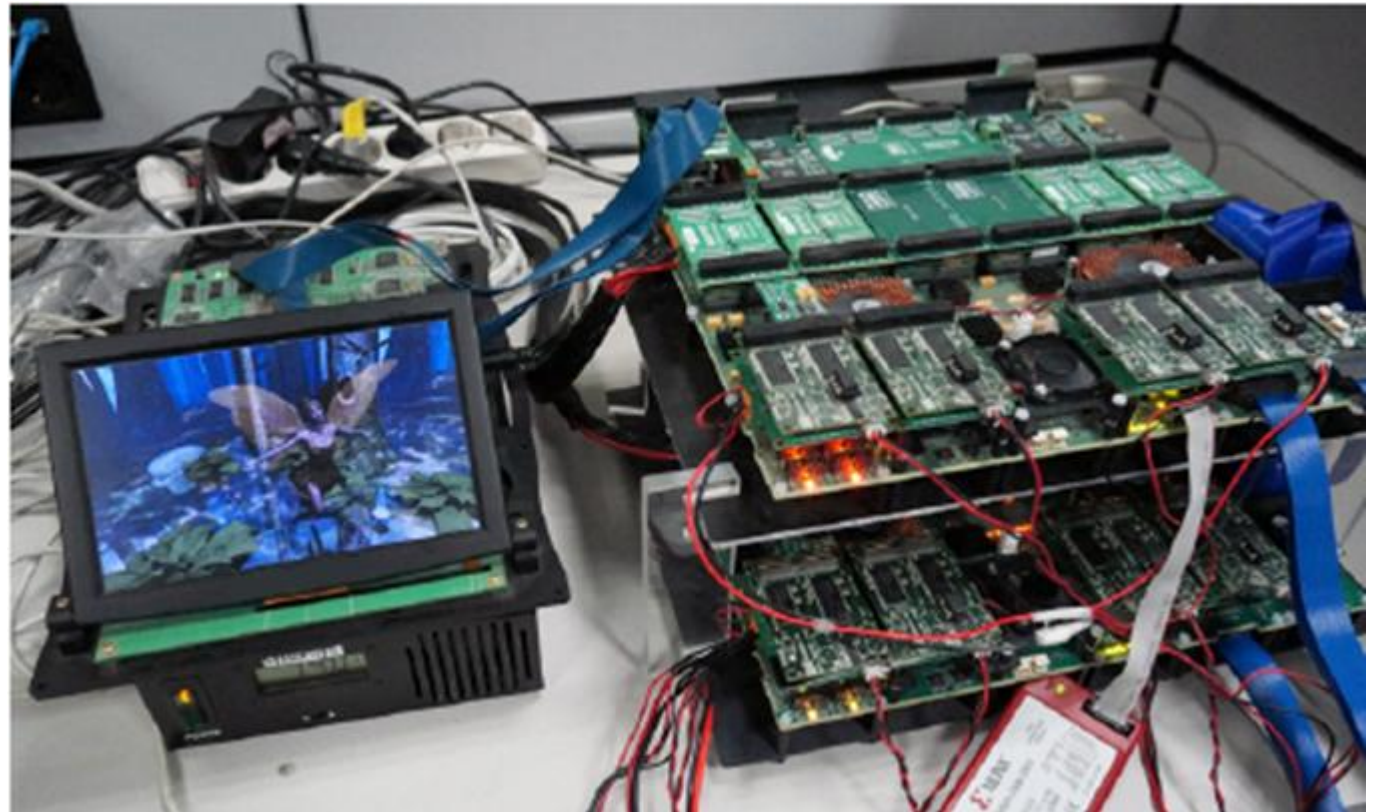
Prototyping challenges

- Mapping ASIC clocking into FPGAs (RTL changes)
- Mapping ASIC memories into FPGAs (RTL changes)
- Interfaces that require speed-adaption (RTL changes)
- Design > 40MG (FPGAs partitioning)
- Debug HW+SW (Tools support)



So ... Traditional prototyping is not suitable anymore

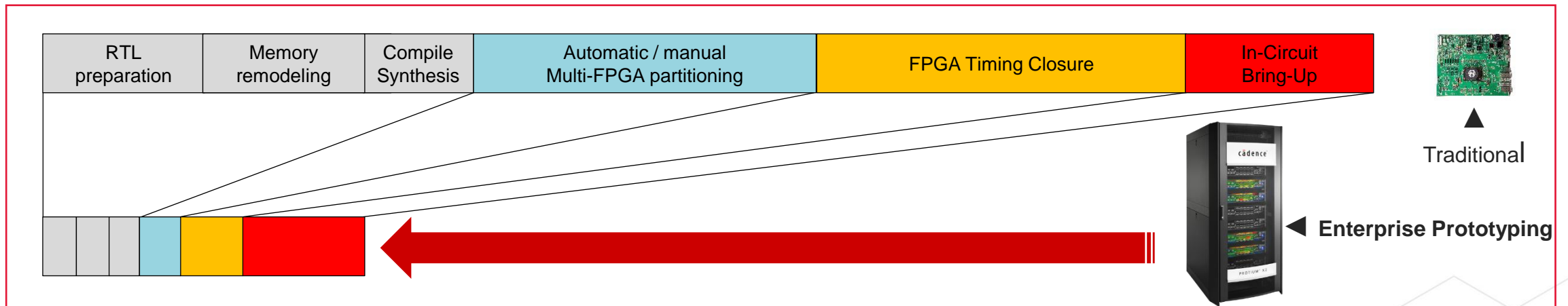
- Too many gates
- Too much memory
- Too many peripherals
- Too much software
- ...
- Not enough time
- Needs to be remotely accessible



And That Brings Us To Enterprise Prototyping ... Addressing Those Challenges!!!

Compiler Automation takes the pain away from mapping to FPGA

- Takes ASIC RTL and with little or no modification maps it into FPGAs
 - Clocks, Memories
 - Fully automatic, multi-FPGA partitioning
 - FPGA timing closure
 - Fully integrated FPGA PnR
 - Speed Bridges, Virtual Bridges, Memory models



Cadence's Dynamic Duo

Palladium



Compile Predictability

Multi-BG Scalability

HW Verification Throughput

9 of the top 10
Hyperscale
Companies

12 of the top 15
Semiconductor
Companies

4 of the top 5
Smartphone / Mobile
Application Processor Suppliers

Protium



High-Perf SW Validation

Multi-BG Scalability


Fast Bring-up via Congruency

6 of the top 10
Hyperscale
Companies

9 of the top 15
Semiconductor
Companies

3 of the top 5
Smartphone / Mobile
Application Processor Suppliers



"Taking a Multi-billion gate design, compiling it and creating emulation model and putting it into the emulator in 4 hours, same process would have taken 24 hours!"




Palladium® Z2 Protium™ X2

The complexity of our high-end graphics and hyperscale designs increases with each generation, while our time-to-market schedules tighten. Using the common front-end flow in the Cadence Palladium Z2 and Protium X2 systems, we are optimizing workload distribution between verification, validation and pre-silicon software bring-up. With twice the useable capacity, 50 percent higher throughput, and faster modular compiler turnaround, we can validate our most sophisticated GPU and SoC designs comprehensively and on schedule.

Narendra Konda
Senior Director, Hardware Engineering





"An important part of AMD's success is to accelerate our product development process and optimize our shift-left strategy. With the Cadence Palladium Z2 and Protium X2 systems' improved performance, we can increase pre-silicon workload throughput, while preserving functional congruency between emulation and prototyping. The ability to perform design bring-up and transition between the Palladium Z2 emulation and the Protium X2 prototyping platforms in a short time provides us with the opportunity to optimize our shift-left deployment for our most challenging SoC designs. With the qualification of servers using the industry-leading third-generation AMD EPYC™ processors with the Palladium Z2 and Protium X2 platforms, customers will be able to bring industry leadership performance compute to the Palladium and Protium ecosystem.



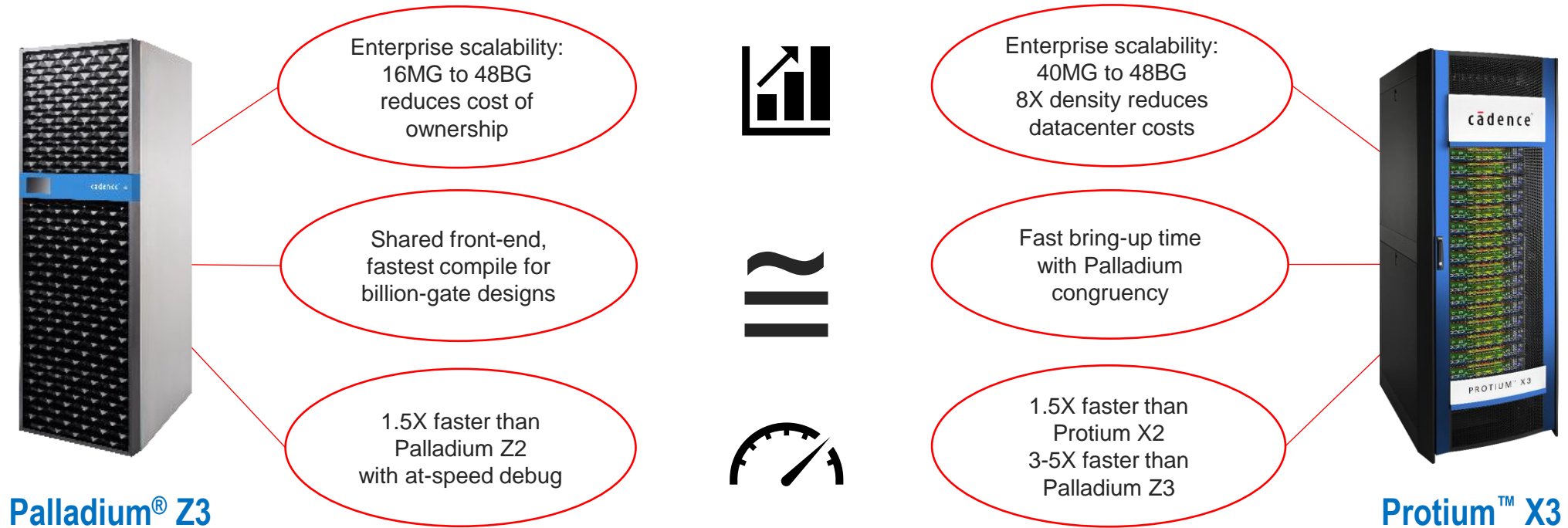
Palladium® Z2 Protium™ X2

Alex Starr
Corporate Fellow, Methodology Architect, AMD



Dynamic Duo III Verification Platforms Benefits

Scalability, Congruency, High performance



Emulation Features and Applications

- Modular Compile: 8-hour TAT for any size design
- FullVision Debug: observe any signal with at-speed triggering
- Exclusive use models: 4-state and mixed-signal emulation, 95% accurate power analysis

Prototyping Features and Applications

- Modular Compile: 24-hour TAT for designs up to 20 BG
- FullVision Debug: observe any signal without recompile
- Shared Virtual and Physical interface and debug solutions with Palladium

Cadence Dynamic Duo III

Unified compile and virtual/physical interfaces

Palladium® Z3



Cadence® Z3
Emulation Processor



3-5X faster
Quick bring-up



Protium™ X3

AMD VP1902
Adaptive SoC



#1 for total TAT

- 1.5x faster than Z2
- 2x more capacity per rack than Z2
- Scalable to 48BG
- Mixed-Signal and 4-state support
- Natively integrated power analysis



#1 for speed

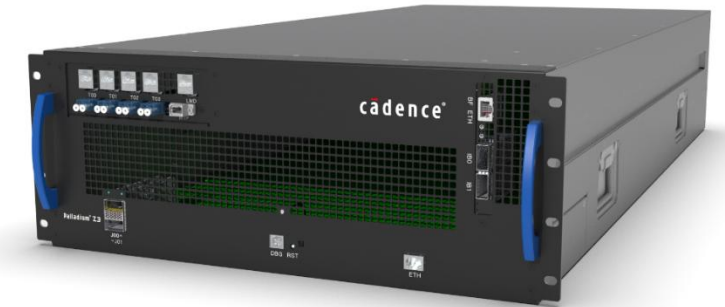
- 1.5x faster than X2
- 3.3x more capacity per rack than X2
- Scalable to 48BG
- Unified compile & testbench link with Z3
- One shot compile technology

Hardware Debug Focus

Software Debug Focus

New! Palladium Z3 System Studio

- Standalone emulator with capacity of 128 million gates
 - No Cadence install required – unpack and go
 - Standalone 4U form factor
 - Air-cooled with front-to-back airflow
 - Powered from typical lab outlets: 110/220V 15/20A
- Supports up to 8 concurrent users per unit
- Supports up to 4 SpeedBridge ports
- Same software and flow as Enterprise Z3 rack system

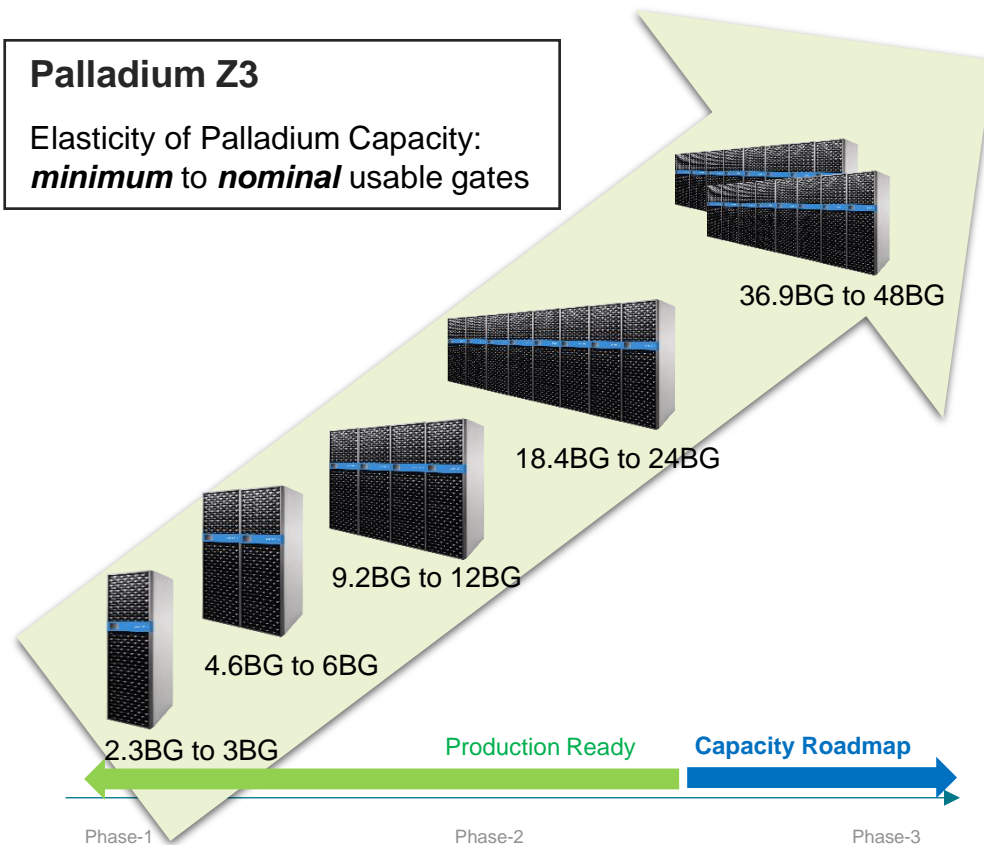


Palladium® Z3
Model: System Studio
Standalone 4U form factor

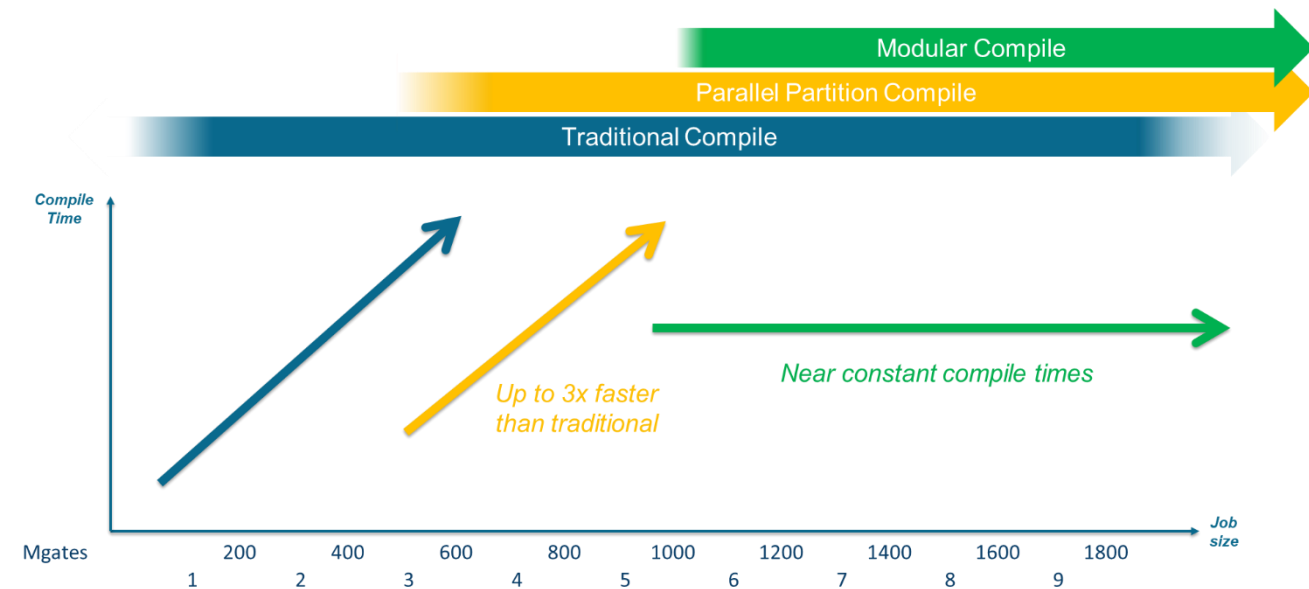
Scaling both **Capacity** and **Compiler** to accommodate rapid design growth

Palladium Z3

Elasticity of Palladium Capacity:
minimum to **nominal** usable gates



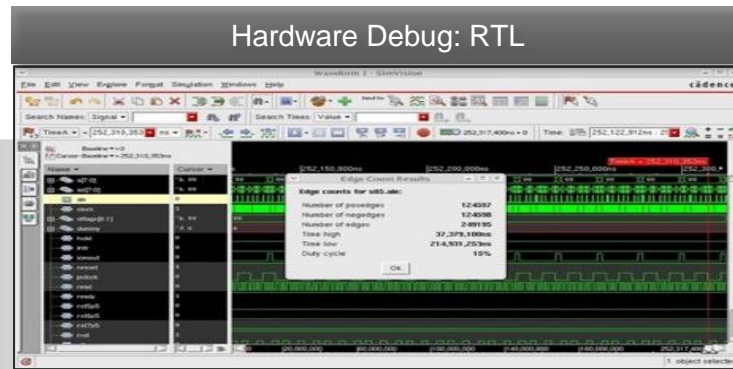
- Z3 capacity scaling to 48BG with user-control granularity of 16MG increments
- Capacity utilization at 100% guaranteed due to processor-based mapping technology



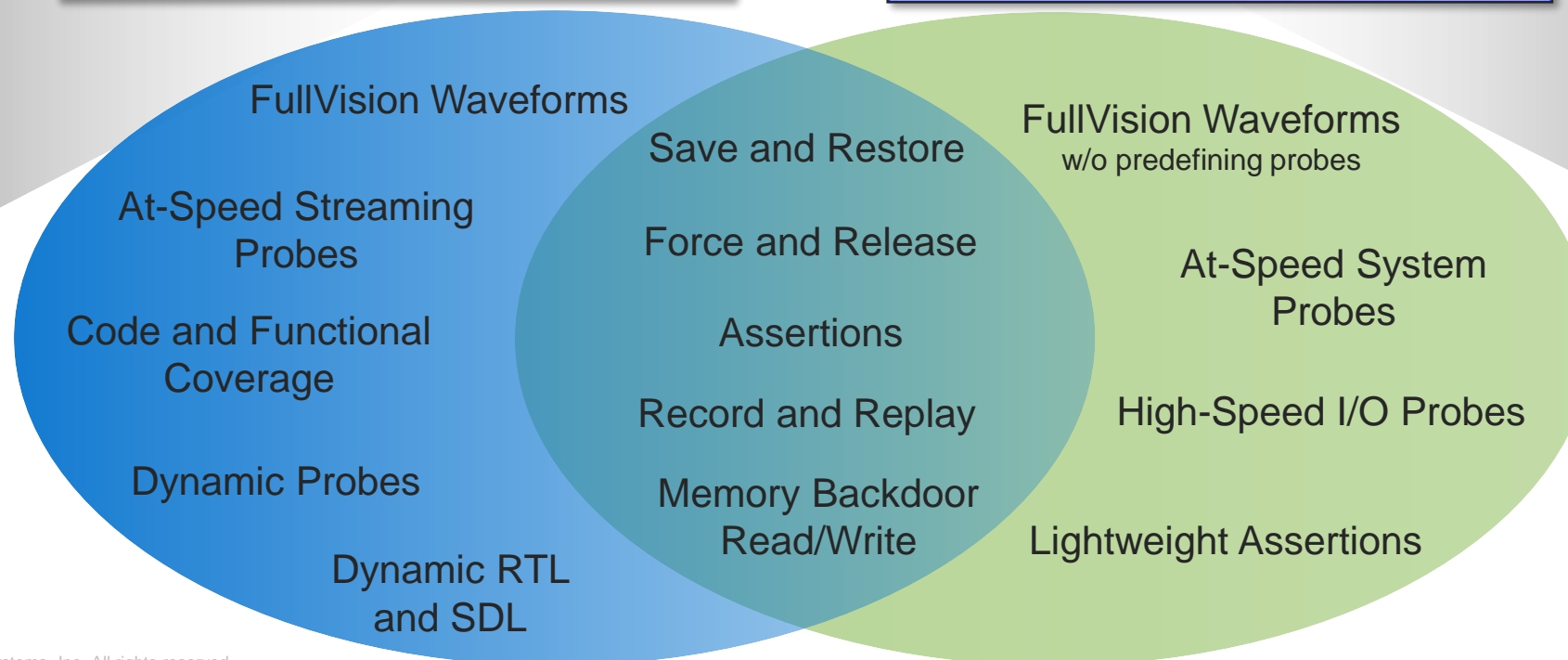
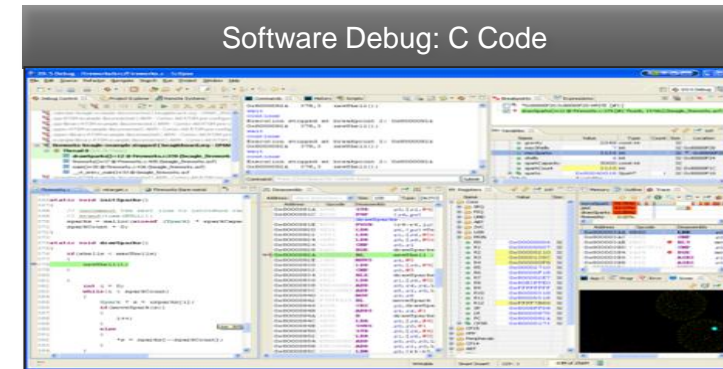
- Modular Compile enables nearly constant compile times based on massively parallelized processor-based compiler with no timing closure required
- Design performance is 100% predictable after compilation

Dynamic Duo III Debug Productivity

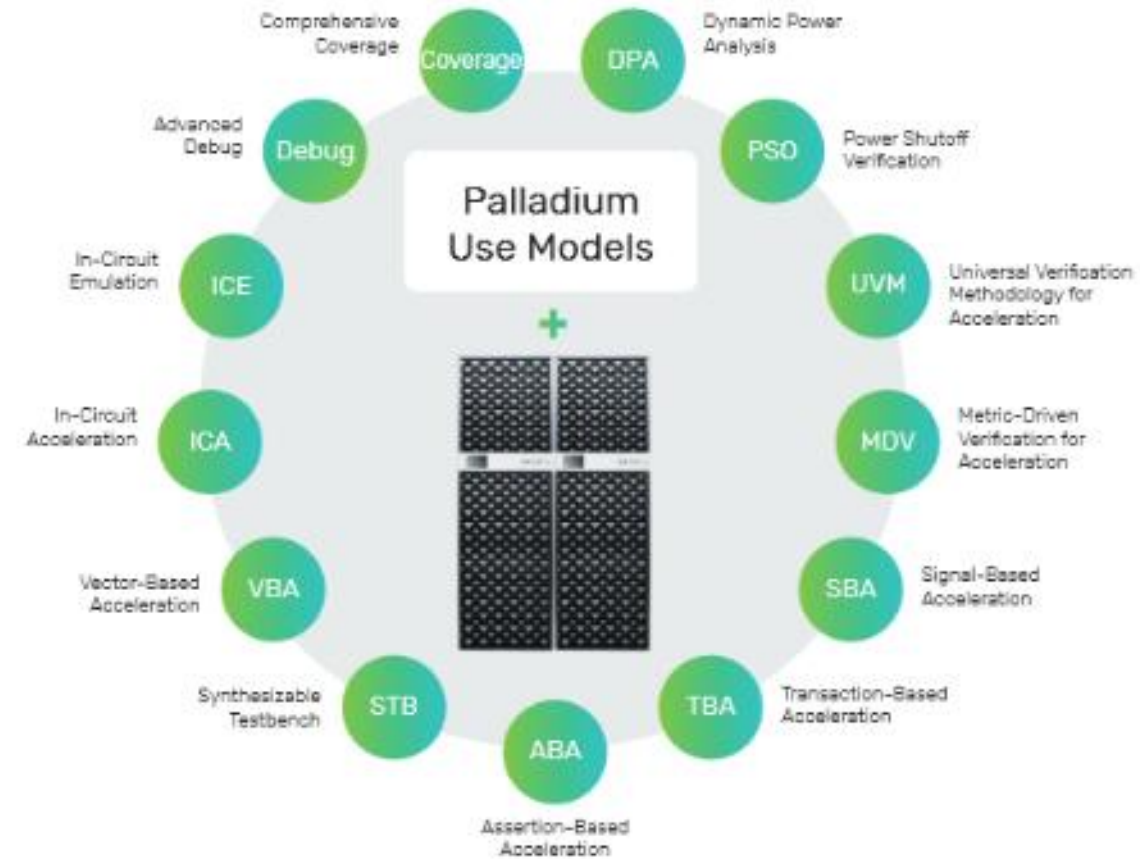
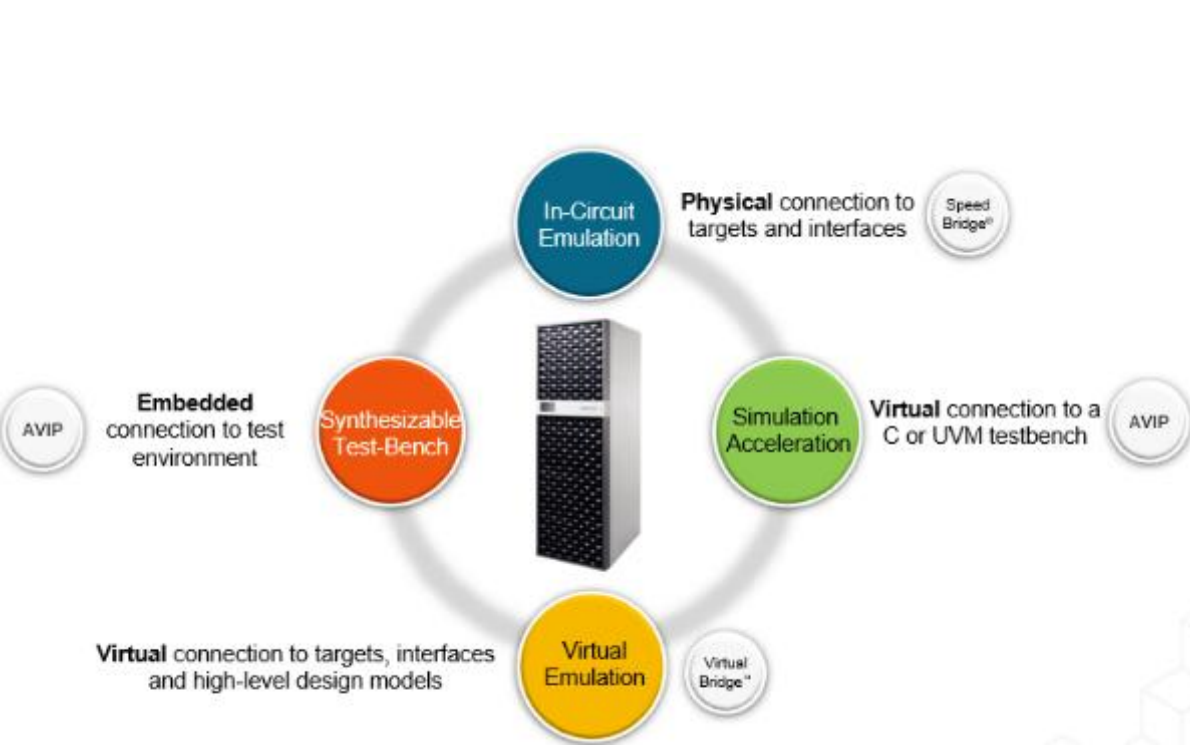
Palladium® Hardware-Focused Debug



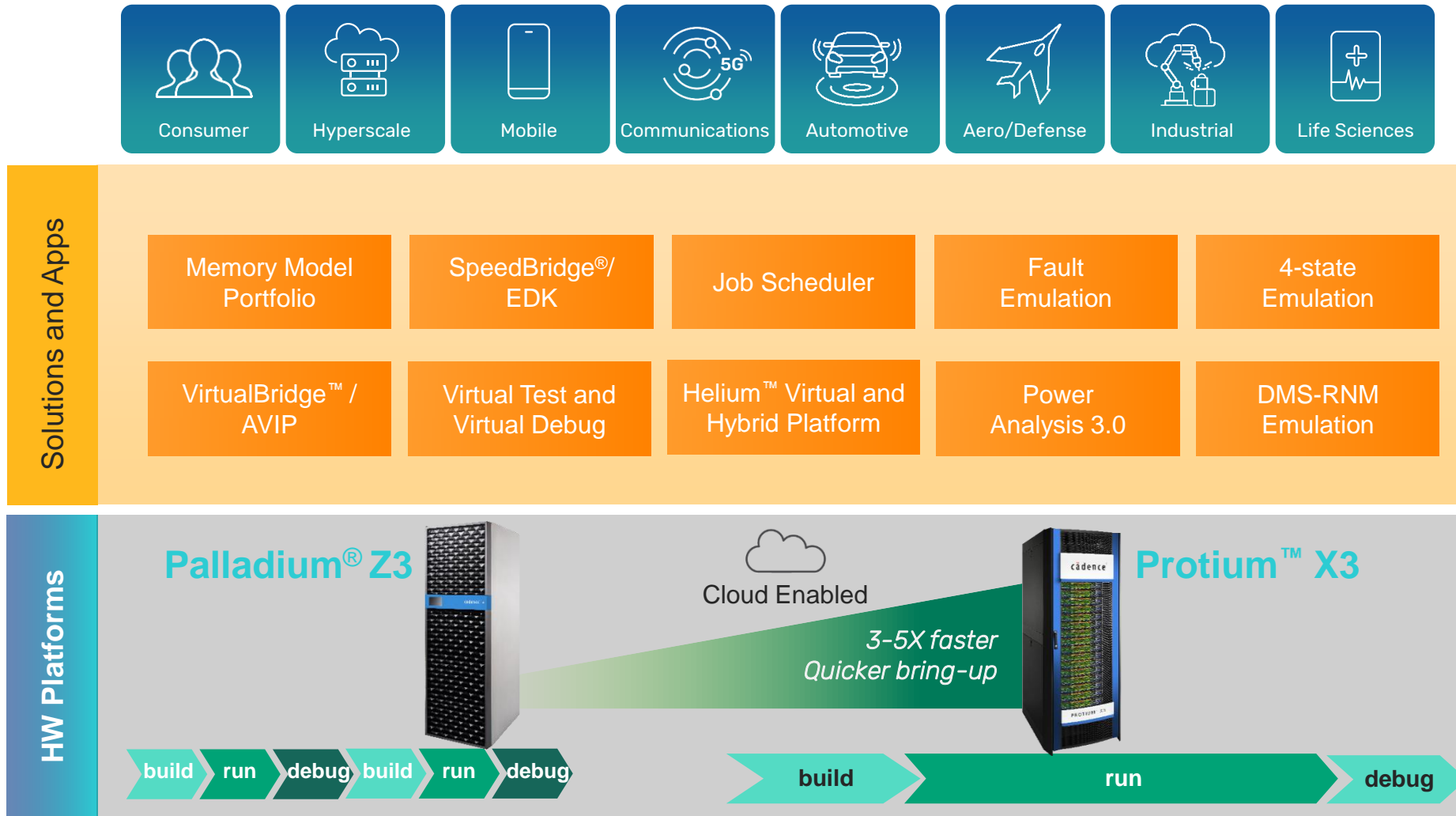
Protium™ Software-Focused Debug



The Many Use Cases of Palladium® Emulation



HW Product Portfolio and Solutions



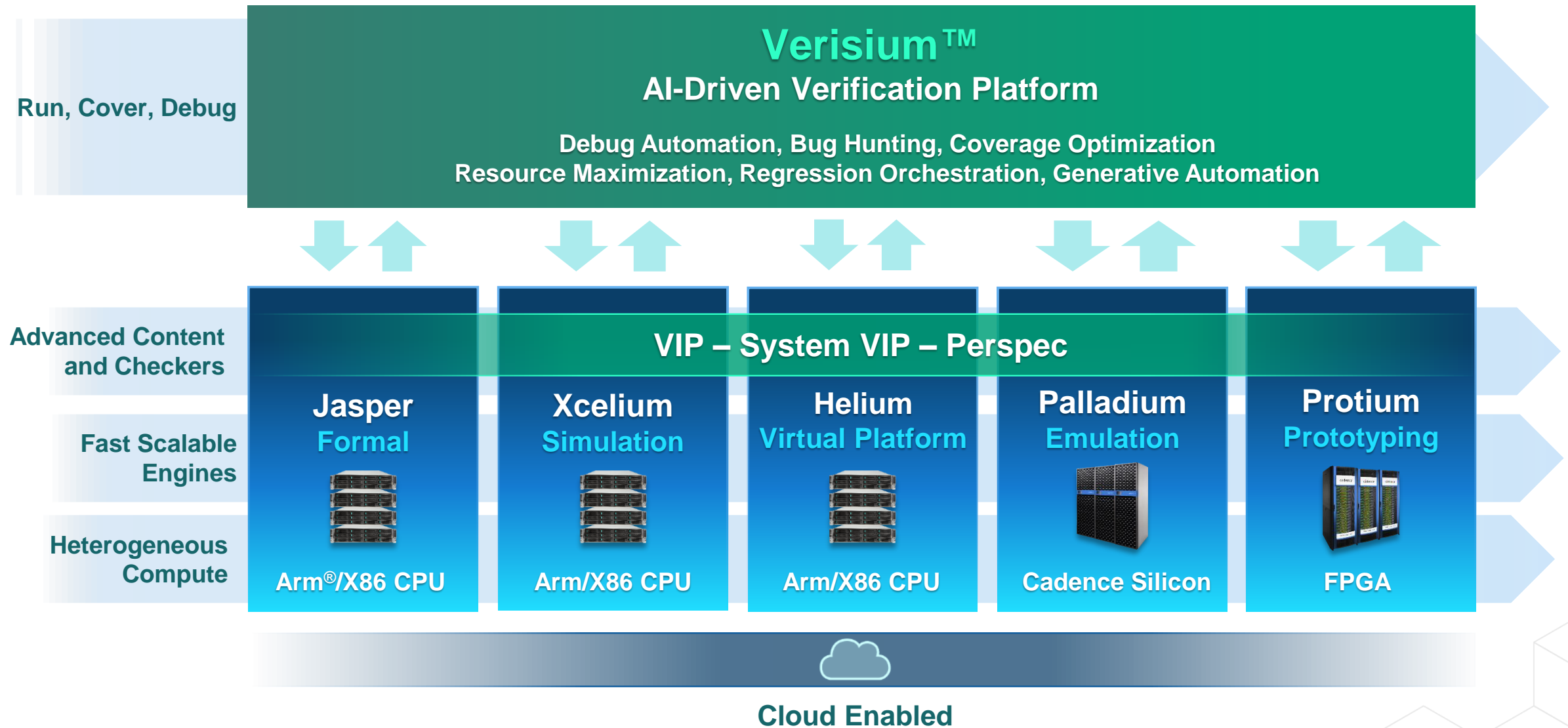
Vertical
Solutions

Acceleration
Engines

Summary

- Software becoming even more important
 - The scope and scale are growing exponentially
 - Timelines are shrinking
- Modern Software Engineering Practices Are Required
 - Cloud-based development environments
 - Automated and continuous integration and regression
- Use the different platforms at different stages of the project
 - Virtual Prototyping
 - Emulation
 - Enterprise Prototyping

Cadence AI-Driven Verification Full Flow





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